

## N-Ch 30V Fast Switching MOSFETs

### Features

- Advanced Trench MOS Technology
- Low  $R_{DS(ON)}$
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Power Management in Desktop Computer
- DC/DC Converters

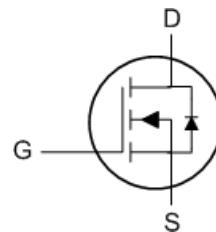
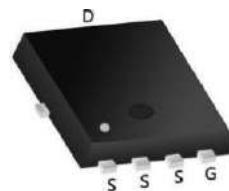
### Product Summary

BVDSS	RDS(on)	ID
30V	2.2mΩ	85A

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	85	A
$I_D @ T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	78	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	250	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	306	mJ
$I_{AS}$	Avalanche Current	35	A
$P_D @ T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	48	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### PRPAK5X6 Pin Configuration



### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	2.6	°C/W

**Electrical Characteristics ( $T_J=25^\circ C$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=20A$	---	1.7	2.2	$m\Omega$
		$V_{GS}=4.5V, I_D=20A$	---	2.4	3.6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.3	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=24V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	$\mu A$
		$V_{DS}=24V, V_{GS}=0V, T_J=55^\circ C$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	1.0	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{DS}=20V, V_{GS}=4.5V, I_D=20A$	---	25.5	---	$nC$
$Q_{gs}$	Gate-Source Charge		---	7.7	---	
$Q_{gd}$	Gate-Drain Charge		---	10.2	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=20V, V_{GS}=10V, R_G=3.3\Omega, I_D=20A$	---	13	---	$ns$
$T_r$	Rise Time		---	5	---	
$T_{d(off)}$	Turn-Off Delay Time		---	39.5	---	
$T_f$	Fall Time		---	12	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	2917	---	$pF$
$C_{oss}$	Output Capacitance		---	1536	---	
$C_{rss}$	Reverse Transfer Capacitance		---	206	---	

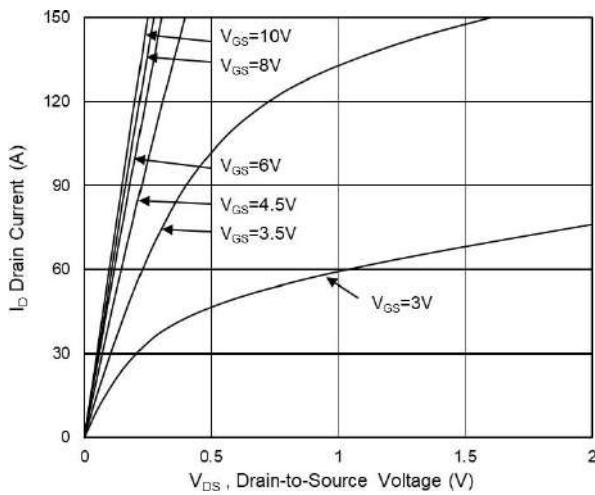
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0V$ , Force Current	---	---	85	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_s=1A, T_J=25^\circ C$	---	---	1.2	V

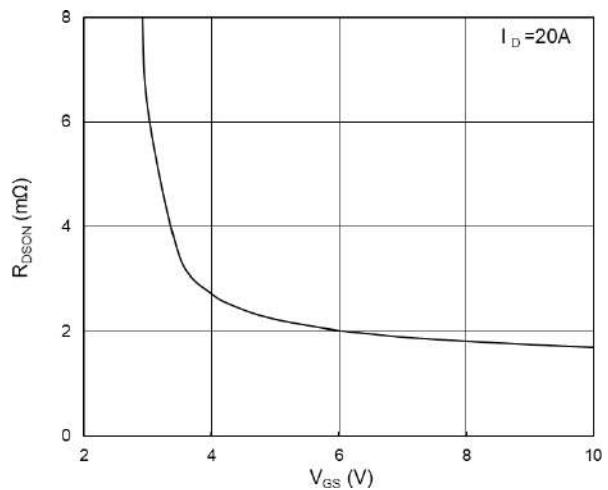
Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.5mH, I_{AS}=35A$
4. The power dissipation is limited by  $150^\circ C$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.
6. Package limitation current is 85A.

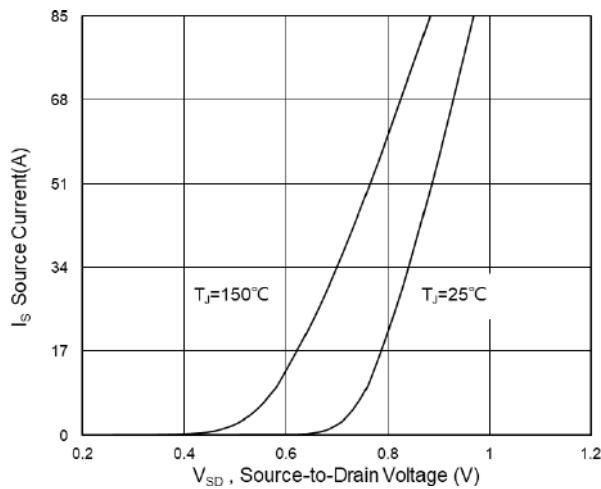
### Typical Characteristics



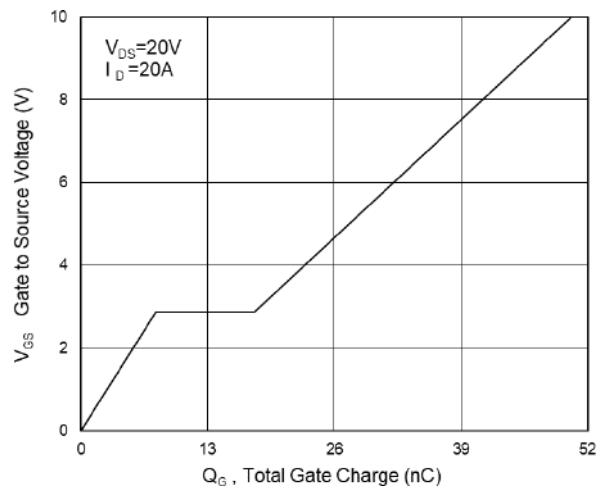
**Fig.1 Typical Output Characteristics**



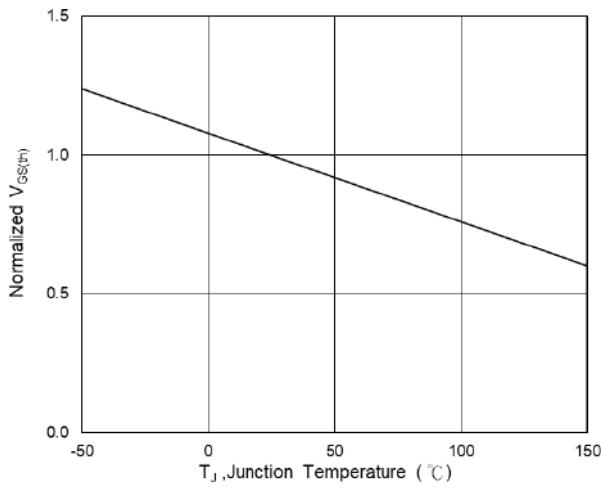
**Fig.2 On-Resistance vs G-S Voltage**



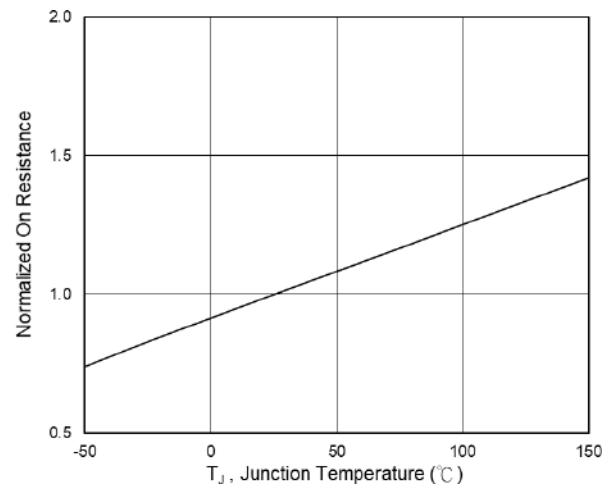
**Fig.3 Source Drain Forward Characteristics**



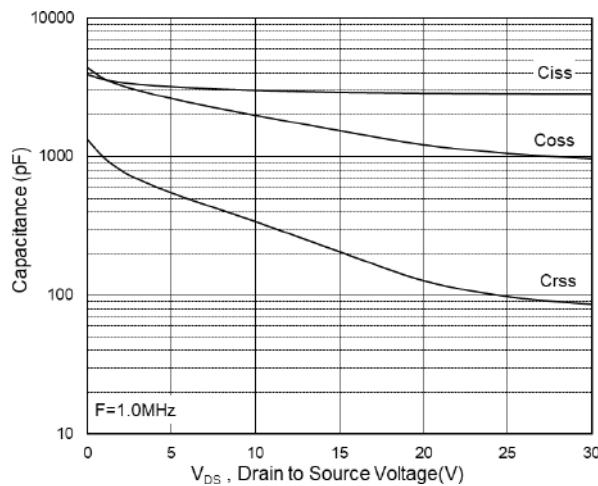
**Fig.4 Gate-Charge Characteristics**



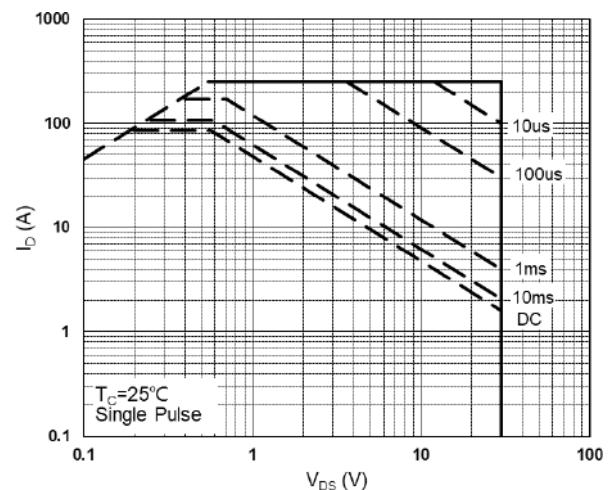
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



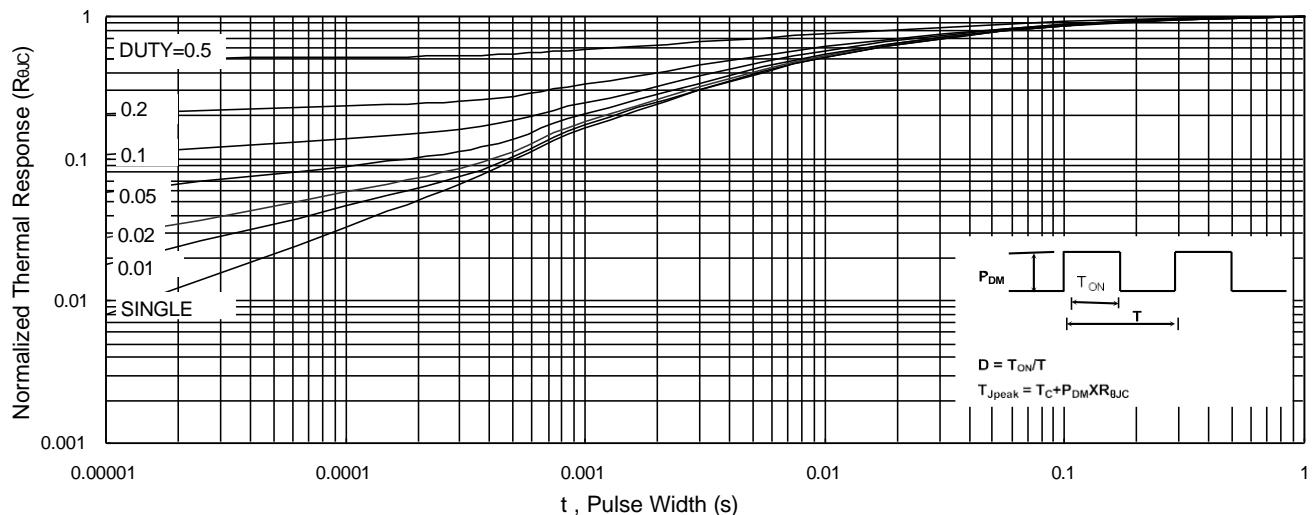
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



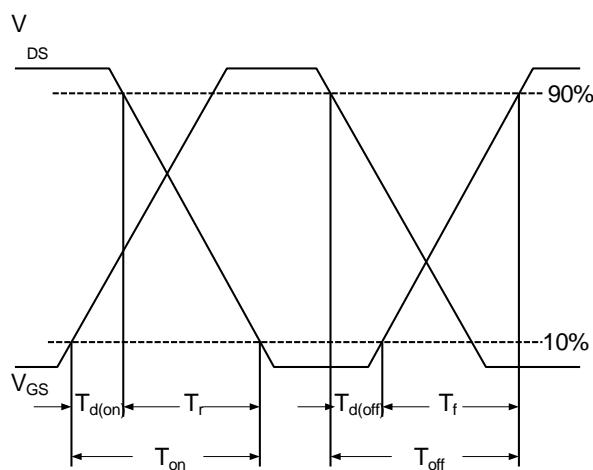
**Fig.7 Capacitance**



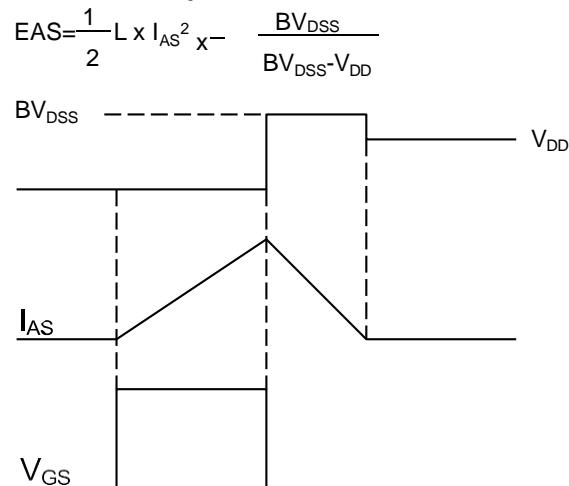
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**